Contact Name Title - Contact Product Enviro Compliance Authorized Representative* Product Enviro Compliance NA Product Enviro Stewards © onsemi.co Na Nanufacturing Site Weight* UOM Nanufacturing Proccess Information Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Natte Tin (Sn) - annealed CU Alloy 1 Seconds 3	LATION CONTROL (Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company unique ID Unique ID Authority Response Date* 2024-05-11 Contact Name Title - Contact Product Env-Stewards Authorized Representative* Product Enviro Compliance Title - Representative Product Enviro Compliance NA Product Env-Stewards Title - Representative Product Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.co NA Namufacturing Site Weight* UOM Wanufacturing Proccess Information Vanufacturing Proccess Information Vanufacturing Proccess Information Terminal Plating / Grid Array Material										als and Mfg	Informat	ion			
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Product-Env-Stewards Authorized Representative* Authorized Representative* Title - Representative Product Enviro Compliance NA Product-Env-Stewards@onsemi.co NA Na Namufacturing Site Weight* UOM NA Namufacturing Proccess Information Vanufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy Namufacturing Product-Env-Stewards@onsemi.co NA Product-Env-Stewards@onsemi.co NA Namufacturing Site Version Manufacturing Site Version	onsemi										2024-05-11				
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Beffective Date Version Manufacturing Site Weight* UOM MANUfacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed CU Alloy Title - Representative Phone - Representative* Bemail - Representative* Product-Env-Stewards@onsemi.co Manufacturing Site Weight* UOM A.58939 mg Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc Number of Reflow Cyc Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Contact Name Ti				Title - Contact			Phone - Contact*				Email - Contact*			
Product Enviro Compliance Requester Item Number Mfr Item Numbe	Product-Env-Stewards				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM MM3Z62VC 62.0V 0.2W 5% Zen SOD323F 2024-05-11 CN2 4.58939 mg Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Authorized Representative* Title - Repre				presentative			Phone - Representative*			Email - Representative*				
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Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester It	tem Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	M	Ianufacturing Site	W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3			MM3Z62	2VC	62.0V 0.2W 5% Ze	en SOD323F		2024-05-11		С	N2	4.	58939	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3				arminal Paga	Alloy	STD 020 MS	I Dating	Dook Proof	oss Pody Tor	maratur	May Time at Book	Tomporatu	n Numb	per of Poflow Cya	los
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		511) - annealeu	C	U Alluy	1			200		<u> </u>	30	second	, 13		
omments vel 1 - maximum time at peak temperature during soldering is 10-30 seconds		a at naak tampawatuw	o during sale	domina is 10.3	20 seconds										
vei 1 - maximum time at peak temperature during soldering is 10-30 seconds or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.03	mg	Supplier	Silicon (Si)	7440-21-3		0.0285	mg
			Supplier	Gold (Au)	7440-57-5		0.0014	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0001	mg
Lead Frame	1.004	mg	Supplier	Silver (Ag)	7440-22-4		0.004	mg
			Supplier	Chromium (Cr)	7440-47-3		0.002	mg
			Supplier	Manganese (Mn)	7439-96-5		0.008	mg
			В	Nickel (Ni)	7440-02-0		0.41	mg
			Supplier	Iron (Fe)	7439-89-6		0.58	mg
Mold Compound-Black	3.44999	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.3736	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0186	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.7179	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.3398	mg
Plating	0.1	mg	Supplier	Tin (Sn)	7440-31-5		0.1	mg
Wire Bond - Cu	0.0054	mg	Supplier	Copper (Cu)	7440-50-8		0.0054	mg